

Test condition:

1. Measure the thermal couple under surface temperature,  $T_c$  is  $58.1^{\circ}\text{C}$
2. TPS54426 the  $\theta_{JC} = 51.3(^{\circ}\text{C}/\text{W})$
3.  $P_D = 0.85$  Watt.
4. This package have the Thermal pad. (We have to mount a PCB).
5. Not include Thermal pad condition  $T_J = 101.7^{\circ}\text{C}$

Question:

How could I evaluation of  $T_J$ ? (Need consider the Thermal pad condition)

Q1. How to use this formula ( $T_J = P_D * \theta_{JC} + T_c$ ) to calculate  $T_J$ ?

(Need consider Thermal pad containing proportional relationship both with  $T_c$ .)

Q2. Why the  $\theta_{JC} > \theta_{JA}$  from the TPS54426 specification?

( formula  $\theta_{JA} = \theta_{JC} + \theta_{JA}$ , normally the  $\theta_{JA} > \theta_{JC}$  )